AMENDMENTS TO THE CLAIMS

Claims 1-14 (Cancelled).

15. (Previously Presented) A wiring board comprising:

an electrically insulating substrate; and

a wiring layer formed on a surface of said electrically insulating substrate by transferring said wiring layer from a wiring transfer sheet, an exposed portion of said surface of said electrically insulating substrate being a rough surface having a plurality of convexities, at least a portion of said convexities each having a diameter in a range of 0.5 μm to 5.0 μm at basis.

16. (Previously Presented) A wiring board comprising:

an electrically insulating substrate; and

a wiring layer formed on a surface of said electrically insulating substrate by transferring said wiring layer from a wiring transfer sheet, an exposed portion of said surface of said electrically insulating substrate being a rough surface having a plurality of convexities, at least a portion of said convexities each having a height in a range of 0.5 μm to 5.0 μm.

17. (Previously Presented) A wiring board comprising:

an electrically insulating substrate; and

a wiring layer formed on a surface of said electrically insulating substrate by transferring said wiring layer from a wiring transfer sheet, an exposed portion of said surface of said electrically insulating substrate being a rough surface having a plurality of convexities, at least a portion of said convexities each having a shape such that sections perpendicular to a height direction of each convexity are not uniform, and such that a maximum-sized section having a maximum area is located at an intermediate position between a basis and a top of each convexity.

18. (Previously Presented) The wiring board of claim 17, wherein at least a portion of said convexities each has a diameter in a range of 0.5 μm to 5.0 μm at the basis, and each has a diameter in a range of 1.0 μm to 10.0 μm at the maximum-sized section.

19. (Currently Amended) ~~A~~ The wiring board of claim 17, wherein: ~~comprising:~~

~~an electrically insulating substrate; and~~

~~a wiring layer formed on a surface of said electrically insulating substrate by transferring said wiring layer from a wiring transfer sheet, an~~ said exposed portion of said surface of said electrically insulating substrate ~~being~~ is an exposed rough surface having ~~a~~ the plurality of convexities, an exposed surface of said wiring layer ~~being~~ is an exposed rough surface having a plurality of convexities ~~formed of particles deposited by electrolytic plating~~, and a surface shape of said exposed rough surface of said electrically insulating substrate ~~being~~ is substantially the same as a surface shape of said exposed rough surface of said wiring layer.

20. (Currently Amended) The wiring board of claim ~~19~~ 17, wherein the wiring transfer sheet includes a carrier base, said wiring layer being formed on a transfer surface of the carrier base prior to being transferred to said electrically insulating substrate, at least a portion of the transfer surface of the carrier base being a roughened surface having concavities formed therein, and said convexities of said ~~exposed~~ rough surface of said electrically insulating substrate being complementary to the concavities of the roughened surface of the carrier base.

21. (Previously Presented) The wiring board of claim 20, wherein the carrier base comprises a first layer and a second layer made of a different material than the first layer, the transfer surface being formed on the first layer, the first layer being formed of a material not soluble with a material of said electrically insulating substrate.

22. (Currently Amended) The wiring board of claim ~~19~~ 17, wherein said convexities of said ~~exposed~~ rough surface of said electrically insulating substrate occupy 50 % to 98 % of said ~~exposed~~ rough surface of said electrically insulating substrate.

23. (Currently Amended) The wiring board of claim ~~19~~ 17, wherein said wiring board comprises a multilayer wiring board including at least two electrically insulating substrates.

24. (Currently Amended) The wiring board of claim 23, wherein said at least two electrically insulating substrates includes:

said electrically insulating substrate comprising a first electrically insulating substrate having said ~~exposed~~ rough surface; and

a second electrically insulating substrate having an exposed rough surface, said second electrically insulating substrate being superposed directly on said ~~exposed~~ rough surface of said first electrically insulating substrate and superposed directly on ~~said~~ an exposed rough surface of said wiring layer formed on said surface of said first electrically insulating substrate.

25. (Currently Amended) The wiring board of claim ~~19~~ 17, further comprising a component connected to said wiring layer and embedded in said electrically insulating substrate.

26. (Currently Amended) The wiring board of claim 25, wherein said electrically insulating substrate comprises a first electrically insulating substrate, said component being arranged to extend within said first electrically insulating substrate and to extend within an adjacent second electrically insulating substrate.

27. (Currently Amended) The wiring board of claim 26, wherein each of said first electrically insulating substrate and said second electrically insulating substrate has through-holes formed in a thickness direction thereof, said through-holes being filled with a conductive paste for electrically connecting a wiring ~~layers~~ layer arranged on ~~surfaces~~ a respective surface of each of said first electrically insulating substrate and said second electrically insulating substrate.

28. (Currently Amended) The wiring board of claim ~~19~~ 17, wherein said electrically insulating substrate has through-holes formed in a thickness direction thereof, said through-holes being filled with a conductive paste for electrically connecting wiring layers formed on opposite surfaces of said electrically insulating substrate.